CD4051B-Q1, CD4052B-Q1, CD4053B-Q1 CMOS ANALOG MULTIPLEXERS/DEMULTIPLEXERS WITH LOGIC-LEVEL CONVERSION

SCHS354A - AUGUST 2004 - REVISED JANUARY 2008

Features

- Qualified for Automotive Applications
- Wide Range of Digital and Analog Signal Levels
 - Digital: 3 V to 20 V
 Analog: ≤ 20 V_{P-P}
- Low ON Resistance, 125 Ω (Typ) Over 15 V_{P-P} Signal Input Range for V_{DD} – V_{EE} = 18 V
- High OFF Resistance, Channel Leakage of ±100 pA (Typ) at V_{DD} - V_{EE} = 18 V
- Logic-Level Conversion for Digital Addressing Signals of 3 V to 20 V (V_{DD} - V_{SS} = 3 V to 20 V) to Switch Analog Signals to 20 V_{P-P} (V_{DD} - V_{EE} = 20 V)
- Matched Switching Characteristics,
 r_{on} = 5 Ω (Typ) for V_{DD} V_{EE} = 15 V

- Very Low Quiescent Power Dissipation Under All Digital-Control Input and Supply Conditions, 0.2 μW (Typ) at V_{DD} – V_{SS} = V_{DD} – V_{EE} = 10 V
- Binary Address Decoding on Chip
- 5-V, 10-V, and 15-V Parametric Ratings
- 100% Tested for Quiescent Current at 20 V
- Maximum Input Current of 1μA at 18 V Over Full Package Temperature Range, 100 nA at 18 V and 25°C
- Break-Before-Make Switching Eliminates Channel Overlap

Applications

- Analog and Digital Multiplexing and Demultiplexing
- Analog-to-Digital (A/D) and Digital-to-Analog (D/A) Conversion
- Signal Gating

description/ordering information

The CD4051B, CD4052B, and CD4053B analog multiplexers are digitally-controlled analog switches that have low ON impedance and very low OFF leakage current. Control of analog signals up to 20 V_{P-P} can be achieved by digital signal amplitudes of 4.5 V to 20 V (If $V_{DD} - V_{SS} = 3$ V, a $V_{DD} - V_{EE}$ of up to 13 V can be controlled; for $V_{DD} - V_{EE}$ level differences above 13 V, a $V_{DD} - V_{SS}$ of at least 4.5 V is required). For example, if $V_{DD} = 4.5$ V, $V_{SS} = 0$ V, and $V_{EE} = -13.5$ V, analog signals from -13.5 V to 4.5 V can be controlled by digital inputs of 0 V to 5 V. These multiplexer circuits dissipate extremely low quiescent power over the full $V_{DD} - V_{SS}$ and $V_{DD} - V_{EE}$ supply-voltage ranges, independent of the logic state of the control signals. When a logic high (H) is present at the inhibit (INH) input, all channels are off.

ORDERING INFORMATION†

TA	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - M	Reel of 2500	CD4051BQM96Q1	CD4051Q
	TSSOP – PW	Reel of 2000	CD4051BQPWRQ1	CM051BQ
-40°C to 125°C	SOIC - M	Reel of 2500	CD4052BQM96Q1§	CD4052Q
-40°C to 125°C	TSSOP – PW	Reel of 2000	CD4052BQPWRQ1§	CD4052Q
	SOIC - M	Reel of 2500	CD4053BQM96Q1	CD4053Q
	TSSOP – PW	Reel of 2000	CD4053BQPWRQ1§	CD4053Q

T For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

[§] Product Preview



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

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description/ordering information (continued)

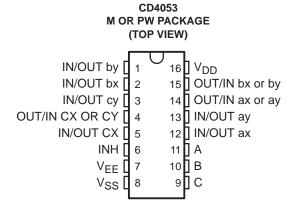
The CD4051B is a single eight-channel multiplexer that has three binary control inputs (A, B, and C) and an inhibit input. The three binary signals select one of eight channels to be turned on and connect one of the eight inputs to the output.

The CD4052B is a differential four-channel multiplexer that has two binary control inputs (A and B) and an inhibit input. The two binary input signals select one of four pairs of channels to be turned on and connect the analog inputs to the outputs.

The CD4053B is a triple two-channel multiplexer with three separate digital control inputs (A, B, and C) and an inhibit input. Each control input selects one of a pair of channels, which are connected in a single-pole, double-throw configuration.

When these devices are used as demultiplexers, the CHANNEL IN/OUT terminals are the outputs, and the common (COM OUT/IN) terminals are the inputs.







Function Tables

CD4051

	INPU	ON		
INH	С	В	Α	CHANNEL
L	L	L	L	0
L	L	L	Н	1
L	L	Н	L	2
L	L	Н	Н	3
L	Н	L	L	4
L	Н	L	Н	5
L	Н	Н	L	6
L	Н	Н	Н	7
Н	Χ	Χ	Χ	None

 \overline{X} = don't care

CD4052

	INPUTS	ON	
INH	В	Α	CHANNEL
L	L	L	0x, 0y
L	L	Н	1x, 2y
L	Н	L	2x, 2y
L	Н	Н	3x, 3y
Н	Χ	Χ	None

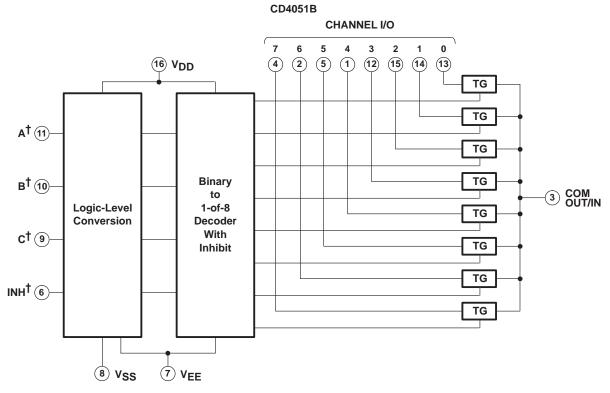
X = don't care

CD4053

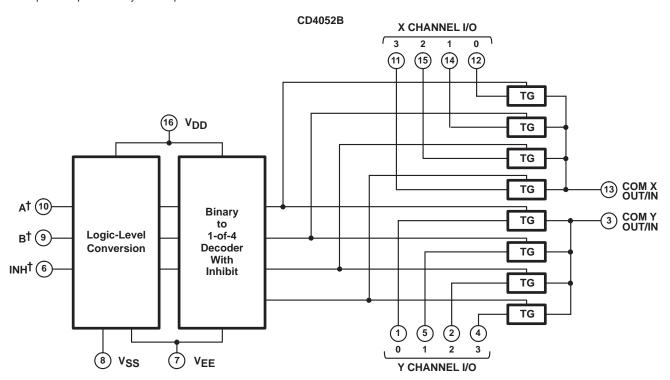
	INPUTS	ON
INH	A OR B OR C	CHANNEL
L	L	ax or bx or cx
L	Н	ay or by or cy
Н	Χ	None

X = don't care

logic diagram (positive logic)



[†] All inputs are protected by CMOS protection network.

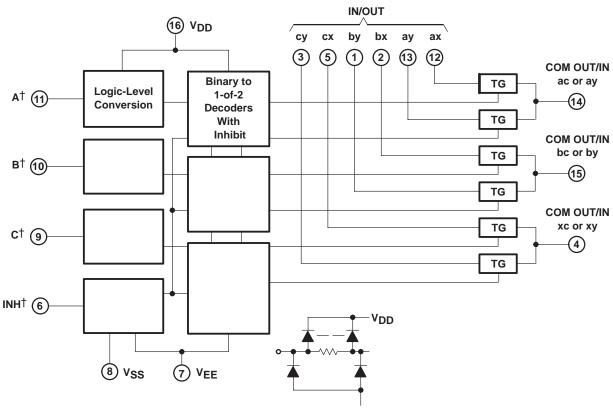


[†] All inputs are protected by CMOS protection network.



logic diagrams (positive logic) (continued)

CD4053B



[†] All inputs are protected by standard CMOS protection network.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)‡

	•
Supply voltage range, V+ to V– (voltages referenced to V _{SS} terminal)	–0.5 to 20 V
DC input voltage range	0.5 V to V _{DD} + 0.5 V
DC input current, any one input	±10 mA
Package thermal impedance, θ _{IA} (see Note 1): M package	
	108°C/W
Maximum junction temperature, T _J	150°C
Lead temperature (during soldering):	
At distance $1/16 \pm 1/32$ inch $(1,59 \pm 0,79$ mm) from case for 10 s m	nax 265°C
Storage temperature range, T _{stg}	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions

		MIN	MAX	UNIT
V_{DD}	Supply voltage	5	20	V
TA	Operating free-air temperature	-40	125	°C

electrical characteristics, V_SUPPLY = ± 5 V, A_V = 1 V, R_L = 100 $\Omega,$ unless otherwise noted (see Note 2)

				V _{DD}	LIMITS AT INDICATED TEMPERATURES						
	PARAMETER	TEST CONDI	TIONS	(V)	4000	42500	25°C			UNIT	
					-40°C	125°C	MIN	TYP	MAX		
				5	5	150		0.04	5		
Inn	Quiescent device			10	10	300		0.04	10	μΑ	
IDD	current			15	20	600		0.04	20	μΑ	
				20	100	3000		0.08	100		
Signal	I Input (V _{iS}) and Outpu	t (V _{OS})									
	Drain-to-source	V 0.V.V 0.V		5	850	1300		470	1050		
ron	ON-state resistance	$V_{EE} = 0 \text{ V}, V_{SS} = 0 \text{ V},$ $V_{IS} = 0 \text{ to } V_{DD}$		10	330	550		180	400	Ω	
		10 0 10 100		15	210	320		125	240		
	ON-state resistance			5				15			
Δr_{on}	difference between	$V_{EE} = 0 V$, $V_{SS} = 0 V$		10				10		Ω	
	any two switches			15				5			
	Input/output leakage current (switch off)	Any channel OFF (MAX) or all channels OFF (COM OUT/IN) (Max), VEE = 0 V, VSS = 0 V, See Note 3		18	±0.1	±1		±10 ⁻⁵	±0.1	μА	
Cis	Input capacitance	$V_{EE} = -5 \text{ V}, V_{SS} = -5 \text{ V}$		5				5		pF	
			CD4051					30			
Cos	Output capacitance	$V_{EE} = -5 \text{ V}, V_{SS} = -5 \text{ V}$	CD4052	5				18		pF	
			CD4053					9			
C _{ios}	Feedthrough capacitance	V _{EE} = -5 V, V _{SS} = -5 V		5				0.2		pF	
	Propagation delay	V D: 00		5				30	60		
tpd	(signal input to	$V_{IS(p-p)} = V_{DD}, R_L = 200$ $C_L = 50 \text{ pF, } t_r, t_f = 20 \text{ ns}$	U K12,	10				15	30	ns	
	output)	r / p/ q ==		15				10	20		

NOTES: 2. Peak-to-peak voltage symmetrical about VDD - VEE

3. Determined by minimum feasible leakage measurement for automatic testing



CD4051B-Q1, CD4052B-Q1, CD4053B-Q1 CMOS ANALOG MULTIPLEXERS/DEMULTIPLEXERS WITH LOGIC-LEVEL CONVERSION SCHS354A - AUGUST 2004 - REVISED JANUARY 2008

electrical characteristics, V_SUPPLY = ± 5 V, A_V = 1 V, R_L = 100 $\Omega,$ unless otherwise noted (see Note 2) (continued)

PARAMETER			VEE	V _{DD}	LIMITS AT INDICATED TEMPERATURES					
		TEST CONDITIONS	(V)	(V)	-40°C	125°C	25°C			UNIT
					-40°C	125°C	MIN	TYP	MAX	
Contr	ol (Address or Inhibit),	Vc								
		$V_{IL} = V_{DD}$ through $1k\Omega$,	VSS	5	1.5	1.5			1.5	
\vee_{IL}	Input low voltage	$V_{IH} = V_{DD}$ through 1kΩ, RL = 1kΩ to V _{SS} ,	VSS	10	3	3			3	V
		I _{is} < 2 μA on all OFF channels	Vss	15	4	4			4	
		$V_{IL} = V_{DD}$ through $1k\Omega$,	Vss	5	3.5	3.5	3.5			
V_{IH}	Input high voltage	$V_{IH} = V_{DD}$ through 1kΩ, $R_{I} = 1$ kΩ to V_{SS} ,	Vss	10	7	7	7			V
		$I_{is} < 2 \mu A$ on all OFF channels	Vss	15	11	11	11			
I _{IN}	Input current	V _{IN} = 0 V, 18 V	•	18	±0.1	±1		±10 ⁻⁵	±0.1	μΑ
	Address-to-signal	t _r , t _f = 20 ns, C _L = 50 pF,	0	5				450	720	ns
	OUT (channels ON	$R_{\rm L} = 10 k\Omega$, $V_{\rm SS} = 0 V$, See Figure 10, Figure 11, and Figure 14	0	10				160	320	
^t pd1	tpd1 or OFF) propagation		0	15				120	240	
	delay		-5	5				225	450	
	Inhibit-to-signal		0	5				400	720	
4	OUT (channel	$t_{\rm r}, t_{\rm f} = 20 \text{ ns}, C_{\rm L} = 50 \text{ pF},$	0	10				160	320	
tpd2	turning ON)	R_L = 1 kΩ, V_{SS} = 0 V, See Figure 11	0	15				120	240	ns
	propagation delay	g .	-10	5				200	400	
	Inhibit-to-signal		0	5				200	450	
OUT (channel	· ·	$t_{\rm f}, t_{\rm f} = 20 \text{ ns}, C_{\rm L} = 50 \text{ pF},$ $R_{\rm L} = 10 \text{ k}\Omega, V_{\rm SS} = 0 \text{ V},$	0	10				90	210	ns
ιbq3	^t pd3 turning OFF)	See Figure 15	0	15				70	160	
	propagation delay		-10	5				130	300	
C _{IN}	Input capacitance, any address or inhibit input							5	7.5	pF

NOTES: 2: Peak-to-peak voltage symmetrical about VDD – VEE

3: Determined by minimum feasible leakage measurement for automatic testing



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electrical specifications

PARAMETER		TEST CONDITIONS			v _{DD}	LIMITS AT INDICATED TEMPERATURES			UNIT
		1_0.00			(V)	25°C			
						MIN	TYP	MAX	
		$R_L = 1 k\Omega$,	CD4053	5	10		30		
	-3-dB cutoff frequency,	V _{OS} at COM OUT/IN, See Note 2,	CD4052	5	10		25		
	channel ON	V _{OS} at COM OUT/IN	CD4051	5	10		20		MHz
	(sine-wave input)	$V_{EE} = V_{SS}$, 20log $V_{OS}/V_{IS} = -3$ dB, V_{OS} at any channel					60		
		5 4010		2	5		0.3		
THD	Total harmonic	$R_L = 10 kΩ$, See Note 2		3	10		0.2		0,
טחו	distortion	See Note 2			15		0.12		%
		$V_{EE} = V_{SS}$, $f_{is} = 1$ -kHz sine wave					0.12		
		$R_L = 1 \text{ k}\Omega$,	CD4053	5	10		8		MHz
	-40-dB	VOS at COM OUT/IN,	CD4052	5	10		10		
	feedthrough frequency	See Note 2	CD4051	5	10		12		
	(all channels OFF)	VEE = VSS, 20log VOS/VIS = -40 dB, VOS at any channel					8		
		$R_L = 1 \text{ k}\Omega$, between any two channels, See	e Note 2	5	10		3		
		VEE = VSS, 20log VOS/VIS = -40 dB, Between sections, Measured on common					6		
	–40-dB signal	VEE = VSS, 20log VOS/VIS = -40 dB, Between sections, Measured on any channel					10		MHz
	crosstalk frequency	VEE = VSS, 20log VOS/VIS = -40 dB, Between any two sections, In pin 2, Out pin 14	004050				2.5		1011 12
Between any tw		V _{EE} = V _{SS} , 20log V _{OS} /V _{IS} = -40 dB, Between any two sections, In pin 15, Out pin 14	wo sections,				6		
	Address or inhibit	R_L = 10 kΩ, See Note 4			10		65		
	to signal crosstalk	$V_{EE} = 0 \text{ V}, V_{SS} = 0 \text{ V}, t_f, t_f = 20 \text{ ns},$ $V_{CC} = V_{DD} - V_{SS} \text{ (square wave)}$					65		m∨peak

NOTES: 2. Peak-to-peak voltage symmetrical about VDD – VEE

4. Both ends of channel



TYPICAL CHARACTERISTICS

CHANNEL ON-STATE RESISTANCE INPUT SIGNAL VOLTAGE 600 Supply Voltage (VDD V_{EE}) = 5 V ron - Channel ON-State Resistance 500 400 300 200 100 Vis - Input Signal Voltage - V 92CS-27326RI

Figure 1

CHANNEL ON-STATE RESISTANCE INPUT SIGNAL VOLTAGE $r_{ m on}$ – Channel ON–State Resistance – Ω = 25°C 300 250 200 150 100 50 Vis - Input Signal Voltage - V 92CS-27330RI

Figure 3

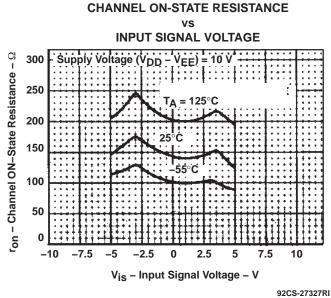


Figure 2

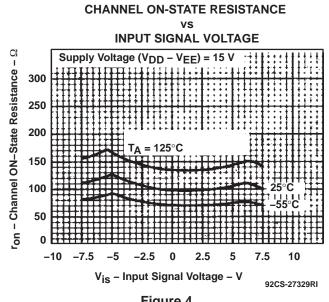


Figure 4

TYPICAL CHARACTERISTICS

ON CHARACTERISTICS FOR 1-OF-8 CHANNELS (CD4051B) $V_{DD} = 5 V$ Vos - Output Signal Voltage - V V_{SS} = 0 V VEE = -5 V **500** Ω 100 Ω T_A = 25°C -6

Figure 5

DYNAMIC POWER DISSIPATION

Vis - Input Signal Voltage - V

SWITCHING FREQUENCY (CD4052B) – Power Dissipation Per Package – μ W T_A = 25°C Alternating ÒOÓ Test Circuit and ÒIÓ Pattern CD4029 $V_{DD} = 15$ 10 ³ 5 2 4 CD4052 G ₹6 7 10

Figure 7

f - Switching Frequency - kHz

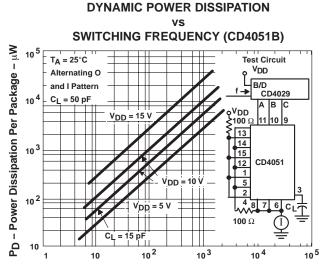
103

10⁴

10⁵

10²

10



f - Switching Frequency - kHz

Figure 6

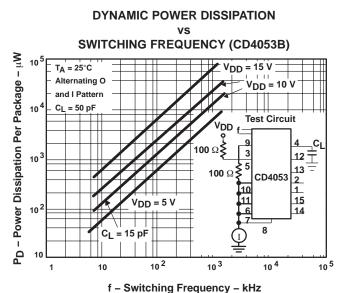
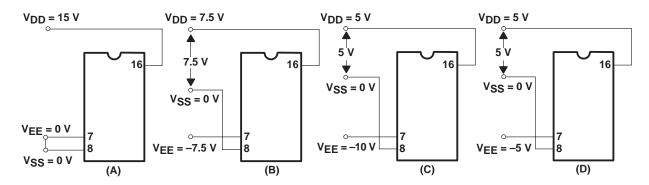


Figure 8



PARAMETER MEASUREMENT INFORMATION



NOTE: The A, B, C, and INH input logic levels are $L = V_{SS}$ and $H = V_{DD}$. The analog signal (through the TG) may swing from V_{EE} to V_{DD} .

Figure 9. Typical Bias-Voltage Test Circuits

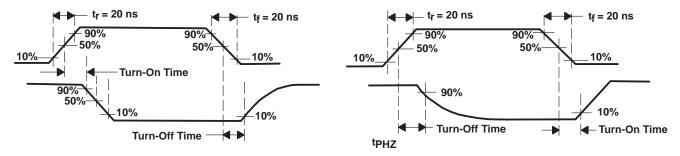


Figure 10. Channel Turned ON Waveforms $(R_L = 1 \text{ k}\Omega)$

Figure 11. Channel Turned OFF Waveforms $(R_L = 1 \text{ k}\Omega)$

PARAMETER MEASUREMENT INFORMATION

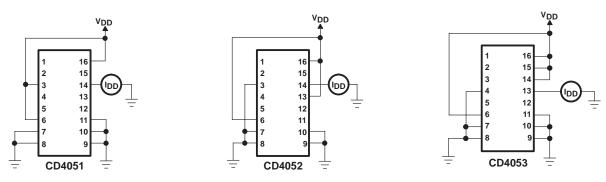


Figure 12. OFF Channel Leakage Current, Any Channel OFF

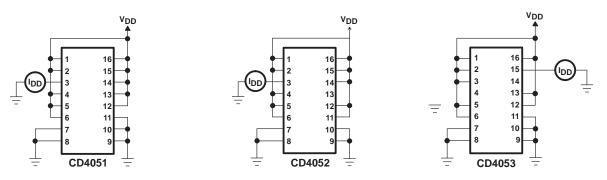


Figure 13. OFF Channel Leakage Current, All Channels OFF

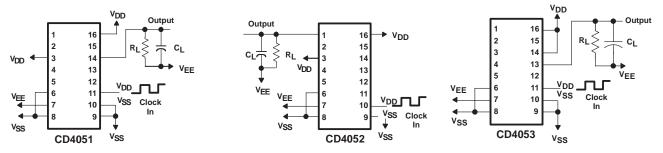


Figure 14. Propagation Delay, Address Input to Signal Output

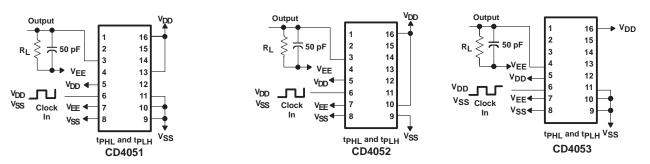
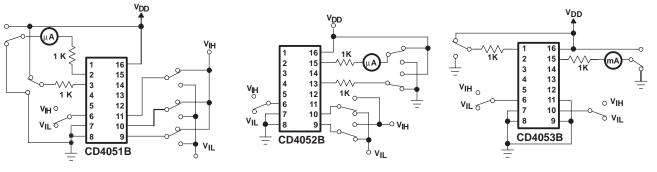


Figure 15. Propagation Delay, Inhibit Input to Signal Output



PARAMETER MEASUREMENT INFORMATION



Measure <2 μ A on All OFF Channels (e.g., Channel 6)

Measure <2 μ A on All OFF Channels (e.g., Channel 2x) Measure <2 μ A on All OFF Channels (e.g., Channel by)

Figure 16. Input-Voltage Test Circuit (Noise Immunity)

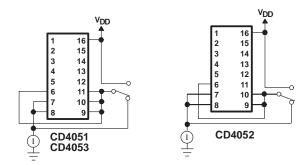


Figure 17. Quiescent Device Current

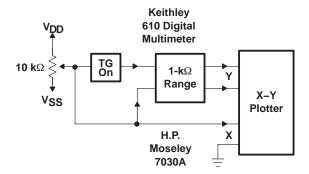
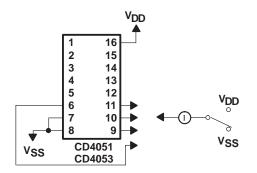
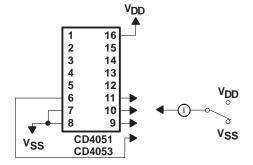


Figure 18. Channel ON-Resistance Test Circuit

PARAMETER MEASUREMENT INFORMATION

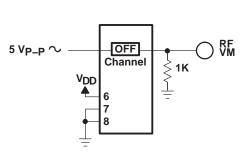




NOTE: Measure inputs sequentially to both V_{DD} and V_{SS} . Connect all unused inputs to either V_{DD} or V_{SS} .

NOTE: Measure inputs sequentially to both V_{DD} and V_{SS} . Connect all unused inputs to either V_{DD} or V_{SS} .

Figure 19. Input Current



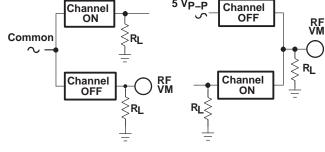


Figure 20. Feedthrough

Figure 21. Crosstalk Between Any Two Channels

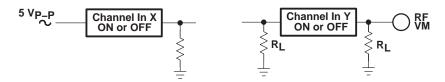


Figure 22. Crosstalk Between Duals or Triplets (CD4052B, CD4053B)

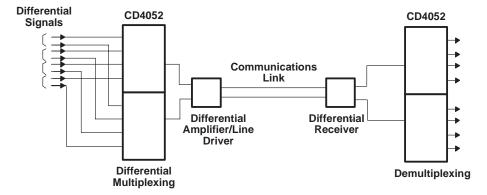


Figure 23. Typical Time-Division Application of the CD4052B



APPLICATION INFORMATION

In applications where separate power sources drive V_{DD} and the signal inputs, the V_{DD} current capability should exceed V_{DD}/R_L (R_L = effective external load). This provision avoids permanent current flow or clamp action on the V_{DD} supply when power is applied or removed from the CD4051B, CD4052B, or CD4053B.

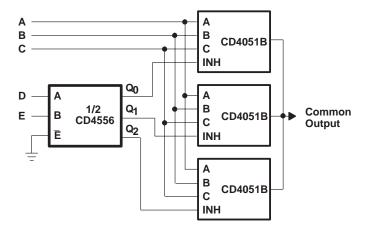


Figure 24. 24-to-1 Multiplexer Addressing



PACKAGE OPTION ADDENDUM

28-Jan-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
CD4051BQPWRQ1	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4053BQM96Q1	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

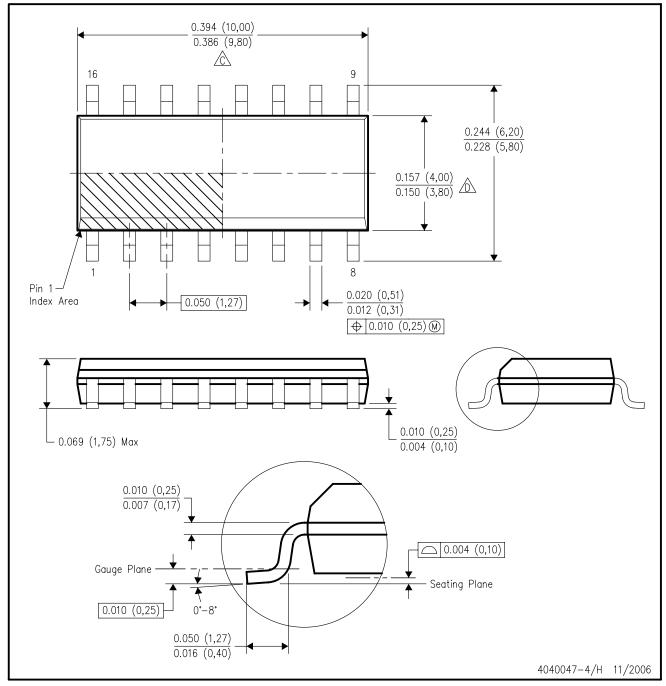
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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